MM5280 4096-Bit (4096 × 1) Dynamic RAM

General Description

National's MM5280 is a 4096 word by 1 bit dynamic RAM. It incorporates the latest memory design features and can be used in a wide variety of applications, from those which require very high speed to ones where low cost and large bit capacity are the prime criteria.

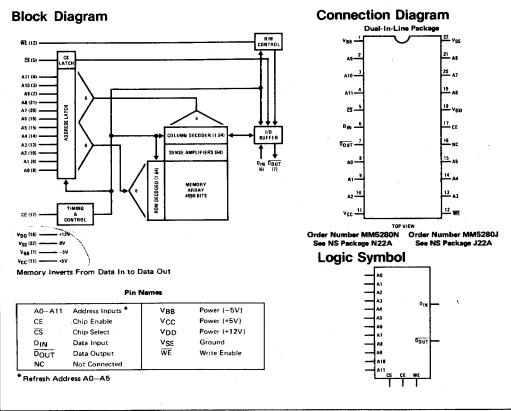
The MM5280 must be refreshed every 2 ms. This can be accomplished by performing a read cycle at each of the 64 row addresses (A0-A5). The chip select input can be either high or low for refresh.

The MM5280 has been designed with minimum production costs as a prime criterion. It is fabricated using N-channel silicon gate MOS technology, which is an ideal choice for high density integrated circuits. The MM5280 uses a single transistor cell to minimize the device area. The single device cell, along with unique design features

in the on-chip peripheral circuits, yields a high performance memory device.

Features

- Organization: 4096 x 1
- Access time 200 ns maximum -
- Cvcle time 400 ns minimum
- Easy system interface
 - One high voltage input—chip enable
- TTL compatible—all other inputs and output
- Address registers on-chip
- TRI STATE® output
- Simple read-modify-write operation
- Industry standard pin configuration



Absolute Maximum Ratings (Note 1)

Storage Temperature -65°C to +150°C
All Input or Output Voltages with Respect
to the Most Negative Supply Voltage, VBB
Supply Voltages VDD, VCC and VSS with -0.3V to +20V

Operating Conditions

MAX UNITS Operating Temperature Range O +70 °c V_{DD} Voltage 10.8 13.2 v V_{CC} Voltage 4.5 5.5 ٧ V_{BB} Voltage -5.5 ٧

DC Electrical Characteristics

Respect to VBB

Power Dissipation

 $T_A = 0^{\circ}\text{C to } + 70^{\circ}\text{C}, \ V_{DD} = (+12\text{V}) \pm 10\%, \ V_{CC} = +5\text{V}) \pm 10\%, \ V_{BB} \ (\text{Note 2}) = -5\text{V} \pm 10\%, \ V_{SS} = 0\text{V}) \text{ unless otherwise noted}$

- 1.25W

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
I _{LI}	Input Load Current	V _{IN} = 0V to V _{IH} max, (All Inputs Except CE)		0.01	10	μΑ
ILC	Input Load Current	V _{IN} = DV to V _{IHC} max		0.01	10	μА
. IILOI	Output Leakage Current Up For High Impedance State	CE = V_{ILC} or $\overline{CS} = V_{IH}$, $V_O = 0V$ to 5.25V		0.01	-10	μΑ
I _{DD1}	V _{DD} Supply Current During CE "OFF"	CE = −1V to +6V, Note 4		110	300	μΑ
I _{DD2}	V _{DD} Supply Current During CE "ON"	CE = V _{IHC} , T _A = 25°C		20	40	mA
OD AV1	Average V _{DD} Current	$T_{\Delta} = 25^{\circ} \text{C}$ Cycle Time = 400 ns, $t_{CE} = 230 \text{ ns}$		35	60	m.A
DD AV2	Average V _{DD} Current	Cycle Time = 1000 ns, t _{CE} = 230 ns	Ì	15	30	mA
leet	V _{CC} Supply Current During CE "OFF"	$CE = V_{ILC} \text{ or } \overline{CS} = V_{IH}$, (Note 5)		0.01	10	μΑ
I _{BB}	V _{BB} Supply Current Average			5	100	μΑ
VIL	Input Low Voltage	t _T = 20 ns (Figure 4)	-1.0	!	0.6	· v
V _{IH}	Input High Voltage		2.4		V _{cc} +1	· v
VILC	CE Input Low Voltage		-1.0		1.0	v
V _{IHC}	CE Input High Voltage		V _{DD} -1	"	V _{DD} +1	v
VoL	Output Low Voltage	I _{OL} = 2.0 mA	0.0		0.45	v
V _{OH}	Output High Voltage	I _{OH} ≈ -2.0 mA	2.4		Vcc	v

Note 1: "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. Except for "Operating Temperature Range" they are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" provides conditions for actual device operation.

Note 2: The only requirement for the sequence of applying voltage to the device is that V_{DD} , V_{CC} , and V_{SS} should never be 0.3V more negative than V_{BB} .

Note 3: Typical values are for $T_A = 25^{\circ}$ C and nominal power supply voltages.

Note 4: The IDD and ICC currents flow to VSS. The IBB current is the sum of all leakage currents.

Note 5: During CE "ON" VCC supply current is dependent on output loading, VCC is connected to output buffer only.

AC Electrical Characteristics $T_A = 0^{\circ}C$ to +70°C, $V_{DD} = 12V \pm 10\%$, $V_{CC} = 5V \pm 10\%$, $V_{BB} = -5V \pm 10\%$

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
READ, WR	ITE, READ/MODIFY/WRITE, AN	D REFRESH CYCLE		·	<u> </u>	
t _{REF}	Time Between Refresh				2	ms
t _{AC}	Address to CE Set-Up Time	tAC is Measured From End of Address Transition	0			ns
tan	Address Hold Time		50			ns
tcc	CE "OFF" Time		130			ns
t _T	CE Transition Time		10		40	ns
t _{CF}	CE "OFF" to Output High					ns
	Impedance State					
READ CYC	LE					
tcy	Cycle Time		400			ns
t _{CE}	CE "ON" Time		230		3000	пs
tco	CE Output Delay	C_{LOAD} = 50 pF, Load = 1 TTL Gate, Ref = 2.0V, t_{ACC} = t_{AC} + t_{CO} + 1 t_{T}			180	ns
tACC	Address to Output Access				200	ns
t _{WL}	CE to WE					ns
twc	WE to CE "ON"		0			ns

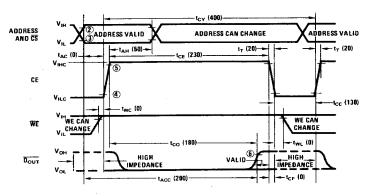
AC Electrical Characteristics (Continued)

 $T_A = 0^{\circ}$ C to +70°C, $V_{DD} = 12V \pm 10\%$, $V_{CC} = 5V \pm 10\%$, $V_{BB} = -5\% \pm 10\%$

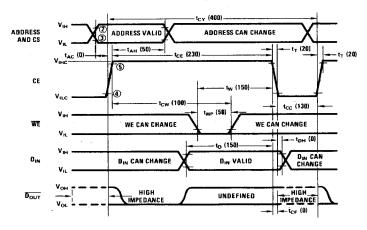
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
WRITE CYC	;LE					
t _{CY}	Cycle Time		400	1	1	ns
t _{CE}	CE "ON" Time		230	1	3000	ns
tw	WE to CE "OFF"		150			ns
tcw	CE to WE	t _T = 20 ns	100			ns
t _D	D _{IN} to CE Set-Up		. 150	İ		ns
t _{DH}	D _{IN} Hold Time		0			ns
twe	WE Pulse Width		50			ns

Switching Time Waveforms





Write Cycle



Note 1: For refresh cycle, row and column addresses must be stable before t_{AC} and remain stable for entire t_{AH} period.

Note 2: V_{1L} max is the reference level for measuring timing of the address, $\overline{\text{CS}}$ and D_{IN} .

Note 3: V_{IH} min is the reference level for measuring timing of the addresses, \overline{CS} and D_{IN} . Note 4: V_{SS} + 2.8V is the reference level for measuring timing of CE.

Note 4: V_{SS} + 2.04 is the reference level for measuring timing of CE.

Note 5: V_{DD} = 2V is the reference level for measuring timing of CE.

Note 6: V_{SS} + 2.0V is the reference level for measuring the timing of D_{OUT} for a high output.

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AC Electrical Characteristics (Continued)

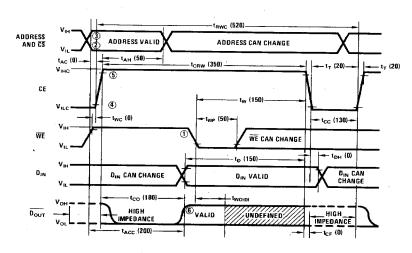
 $T_A = 0^{\circ} C \text{ to } +70^{\circ} C$, $V_{DD} = 12V \pm 10\%$, $V_{CC} = 5V \pm 10\%$, $V_{BB} = -5\% \pm 10\%$

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
READ/MOD	DIFY/WRITE CYCLE					
^t ewc	Read Modify Write (RMW) Cycle Time		520		Ī	ns
tcsw	CE Width During RMW		350		3000	ns
twc	WE to CE "ON"	•	0			ns
tw	WE to CE "OFF"		150		ļ	ns
twe	WE Pulse Width	$t_T = 20 \text{ ns, } C_{LOAD} = 50 \text{ pF, Load} = 1 \text{ TTL Gate,}$ Ref = 2.0V, $t_{ACC} = t_{AC} + t_{CO} + 1 t_T$	50		l	ns
t _D	D _{IN} to CE Set-Up	LOU, LACC LAC LEGO LIT	150			ns
toH	D _{IN} Hold Time	İ	0			ns
tco	CE to Output Delay		-	1	180	ns
t_{WO}	WE to D _{OUT} Invalid		0			
tACC	Access Time				200	กร
CAPACITAN	ICE (Note 1)	$T_A = 25^{\circ}C$	<u> </u>	L	L	
CAD	Address Capacitance, CS	V _{IN} = V _{SS}		2	[ρF
C_{CE}	CE Capacitance	V _{IN} = V _{SS}		15		рF
c_{out}	Data Output Capacitance	V _{O∪7} = 0V		5		pF
CIN	D _{IN} and WE Capacitance	VIN = VSS		4		pF

Note 1: Capacitance measured with Boonton Meter or effective capacitance calculated from the equation $C = I\Delta t/\Delta V$ with the current equal to a constant 20 mA.

Switching Time Waveforms (Continued)

Read Modify Write Cycle



Note 1: \overline{WE} must be high until end of t_{CO} .

Note 2: V_{IL} max is the reference level for measuring timing of the address, CS, D_{SN} and WE.

Note 3: V_{IH} min is the reference level for measuring timing of the address, \overline{CS} , D_{IN} and \overline{WE} .

Note 4: V_{SS} + 2.0V is the reference level for measuring timing of CE.

Note 5: $V_{DD} = 2V$ is the reference level for measuring timing of CE.

Note 6: V_{SS} + 2.0V is the reference level for measuring the timing of $\overline{D_{OUT}}$ for a high output.